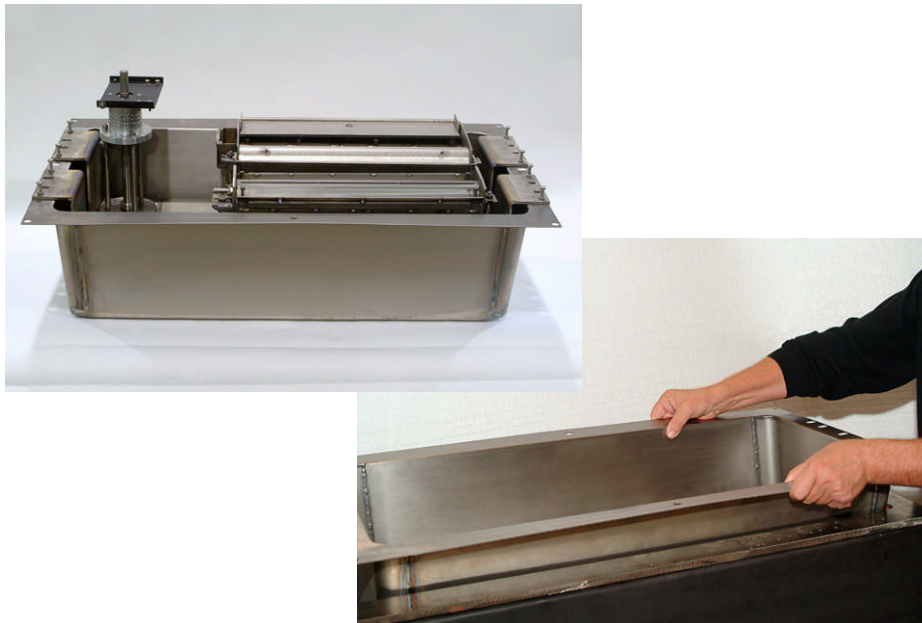




Specnor Tecnic

Lead-Free Retrofit Kit



The Lead-Free Retrofit Kit is an inexpensive solution to upgrade an existing wave solder machine for lead-free operation without the cost of purchasing a new wave solder machine or replacing the entire solder pot. Made of all titanium construction, the Lead-Free Retrofit Kit is highly resistant to the corrosive effects of lead-free solders and affords significantly improved longevity compared to surface coated alternatives.

Winner of the coveted 2005 SMT Vision Award, the innovative Lead-Free Retrofit Kit is compatible with all major brands of wave solder machines and can be easily installed in all popular wave machine models.

Features

- Eliminates iron and copper dissolution associated with uncoated stainless steel or cast iron solder pots
- Offers consistent performance and eliminates periodic replacement of wear parts such as impellers, flow ducts and solder nozzles
- Impervious to de-dross scratching that can damage surface coated metal parts
- Fully optimized solder flow for lead-free operation and compatible with all lead-free and tin-lead solder alloys
- Can be installed in all popular models of wave solder machines and field retrofitted without exchanging the solder pot
- Competitively priced compared to surface coated alternatives



Lead-Free Retrofit Kit Specifications:

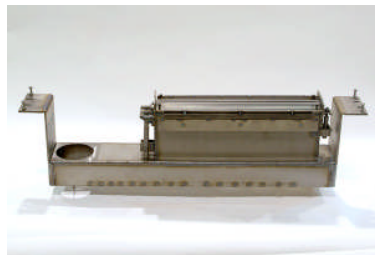
Retrofit Kit Includes

Titanium solder pot liner
 Titanium impellers
 Titanium solder pump assemblies
 Titanium solder nozzles
 Titanium flow ducts
 New temperature switches and solder level sensors
 All other parts in contact with molten solder made of titanium

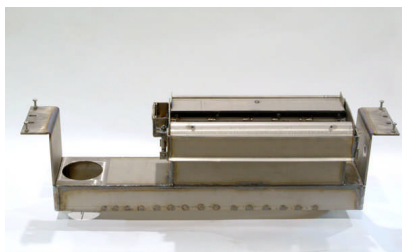


Titanium Solder Pot Liner

Retrofit Kit Assemblies



Titanium Chip Wave Assembly



Titanium Laminar Wave Assembly

Available For

All major brands and most popular models of wave solder machines, including:

Electrovert™
 ERSA™
 Seho™
 Specnor™
 Tamura™
 Technical Devices™
 Vitronics Soltec™

Contact us to review your application requirements and for the name of your local representative.

Retrofit Kit Compatibility with All Lead-Free Solder Alloys

Characteristics of Lead-Free Alloys			
Solder Alloy	Melting Point	Solder Pot Temperature	Density
SnCu	227°C	270-280°C	7.29
SnAg	221°C	265-275°C	7.44
SnAgCu	217°C	260-270°C	7.38
SnAgCuSb	217°C	260°C	7.24
SnPb	183°C	250°C	8.80

Longevity of Lead-Free Retrofit Kit

Summary of Base Metals			
Material	Advantages	Disadvantages	Longevity*
Titanium	Excellent resistance to effects of tin	Can be expensive to fabricate	10 years
304 stainless steel	Inexpensive	No corrosion resistance	1 month
316 stainless steel	Inexpensive	No corrosion resistance	3-6 months
Surface coated stainless steel	Good resistance to effects of tin	Will degrade if scratched	6-12 months
Surface coated cast iron	Inexpensive	Will degrade if scratched	1-2 years

* - Under sustained production conditions with SAC 305 lead-free solder alloy

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